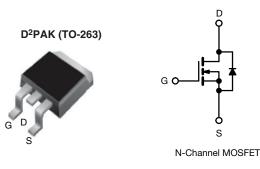
Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	850				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	1.1			
Q _g max. (nC)	32				
Q _{gs} (nC)	4				
Q _{gd} (nC)	6				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION	
Package	D ² PAK (TO-263)
Lead (Pb)-free and halogen-free	SiHB4N80E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \text{ °C}$, unless otherwise noted)							
PARAMETER	SYMBOL	LIMIT	UNIT				
Drain-source voltage		V _{DS}	800	V			
Gate-source voltage	V _{GS}	± 30	v				
Continuous drain current (T _J = 150 °C)	$V_{GS} \text{ at } 10 \text{ V} \qquad \frac{T_{C} = 25}{T_{C} = 100}$	°C	4.3				
	V_{GS} at 10 V $T_C = 100$) °C	2.7	А			
Pulsed drain current ^a	I _{DM}	11					
Linear derating factor		0.56	W/°C				
Single pulse avalanche energy ^b	E _{AS}	56	mJ				
Maximum power dissipation	PD	69	W				
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C			
Drain-source voltage slope	T _J = 125 °C	d\//dt	70	V/ns			
Reverse diode dV/dt ^d		dV/dt	0.3	V/ns			
Soldering recommendations (peak temperature) ^c	For 10 s		260	°C			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.0 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C

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COMPLIANT

HALOGEN

FREE

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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	-		62		°C/W		
Maximum junction-to-case (drain)	R _{thJC}	- 1.8				C/W		
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u		ise noted)			1	•	1	
PARAMETER	SYMBOL	TES		ONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 25	50 µA	800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I	_D = 1 mA	-	1.1	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 28$	50 µA	2.0	-	4.0	V
Gate-source leakage			$V_{GS} = \pm 20 V$		-	-	± 100	nA
Gale-Source leakage	GSS	\ \	√ _{GS} = ± 30 \	/	-	-	± 1	μA
Zaus and a subtant due in assured		V _{DS} =	800 V, V _{GS}	= 0 V	-	-	1	
Zero gate voltage drain current	IDSS	V _{DS} = 640 V	, $V_{GS} = 0 V$,	T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V		= 2 A	-	1.1	1.27	Ω
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 2 A		-	1.5	-	S	
Dynamic		•				•		
Input capacitance	C _{iss}		V _{GS} = 0 V,		-	622	-	
Output capacitance	C _{oss}	· ·	$V_{\rm DS} = 100 \text{ V},$ f = 1 MHz		-	34	-	-
Reverse transfer capacitance	C _{rss}				-	5	-	
Effective output capacitance, energy related ^a	C _{o(er)}			-	21	-	pF	
Effective output capacitance, time related ^b	C _{o(tr)}	$ V_{DS} = 0$ V	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	91	-	
Total gate charge	Qg				-	16	32	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	I _D = 2 A,	A, V _{DS} = 480 V	-	4	-	nC
Gate-drain charge	Q _{gd}				-	6	-	
Turn-on delay time	t _{d(on)}				-	12	24	
Rise time	t _r	Voo =	V _{DD} = 480 V, I _D = 2 A,		-	7	14	1
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$ f = 1 MHz, open drain		-	26	52	ns	
Fall time	t _f			-	20	40		
Gate input resistance	R _g			0.6	1.2	2.4	Ω	
Drain-Source Body Diode Characteristic	÷				<u> </u>		<u>.</u>	
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	4.4		
Pulsed diode forward current	I _{SM}			-	-	11	A	
Diode forward voltage	V _{SD}	T _{.1} = 25 °C, I _S = 2 A, V _{GS} = 0 V			-	-	1.2	V
ÿ	55				1			┝───

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}

t_{rr}

Q_{rr}

I_{RRM}

Reverse recovery time

Reverse recovery charge

Reverse recovery current

 $\begin{array}{l} T_J=25~^\circ\text{C},~I_F=I_S=2~\text{A},\\ dI/dt=100~\text{A}/\mu\text{s},~V_R=25~\text{V} \end{array}$

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248

1.4

9.2

_

-

-

496

2.8

-

ns

μC

А



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

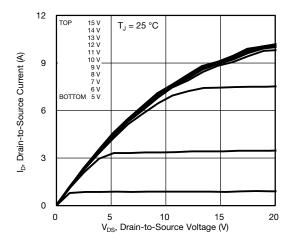
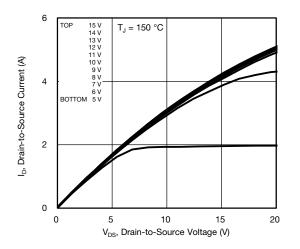


Fig. 1 - Typical Output Characteristics





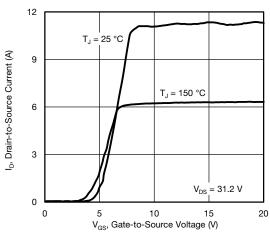


Fig. 3 - Typical Transfer Characteristics

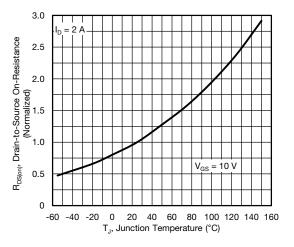


Fig. 4 - Normalized On-Resistance vs. Temperature

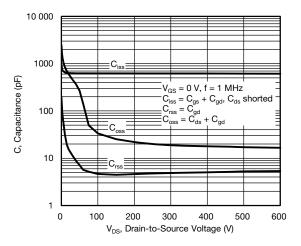


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

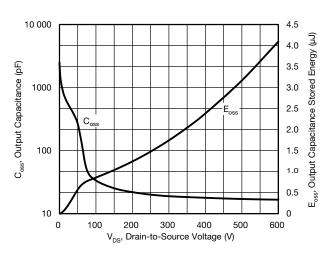


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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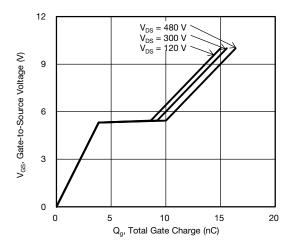


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

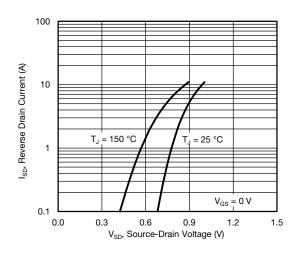


Fig. 8 - Typical Source-Drain Diode Forward Voltage

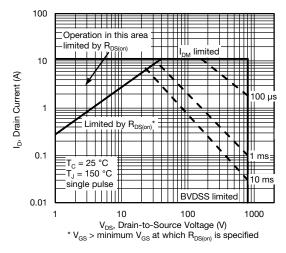


Fig. 9 - Maximum Safe Operating Area

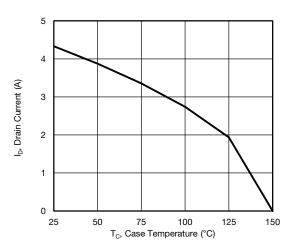


Fig. 10 - Maximum Drain Current vs. Case Temperature

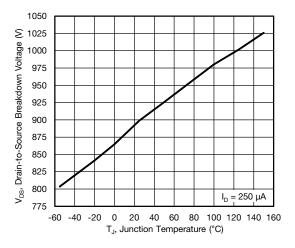
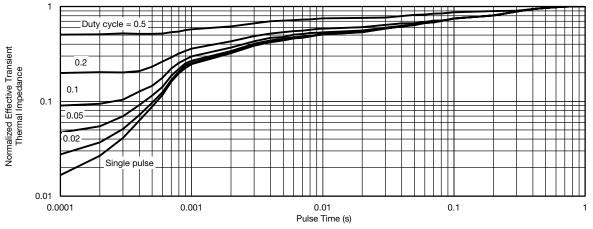


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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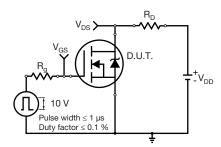


Fig. 13 - Switching Time Test Circuit

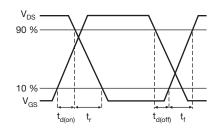


Fig. 14 - Switching Time Waveforms

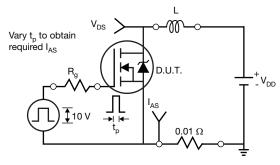


Fig. 15 - Unclamped Inductive Test Circuit

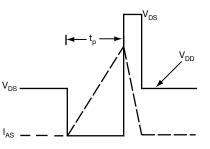


Fig. 16 - Unclamped Inductive Waveforms

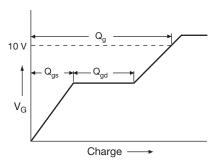


Fig. 17 - Basic Gate Charge Waveform

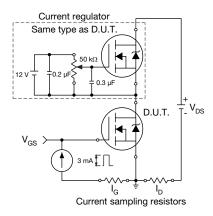


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit

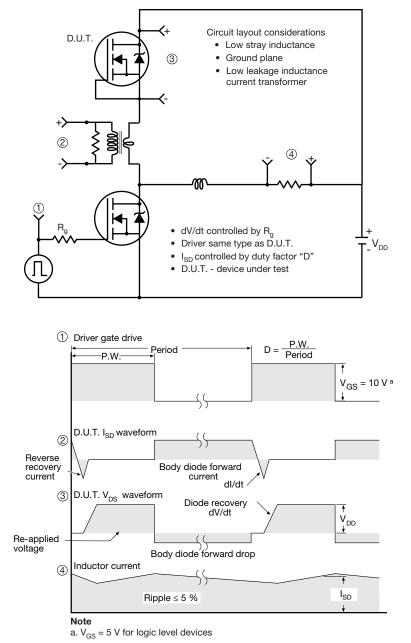


Fig. 19 - For N-Channel

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